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Error Prevention for µ-Components on Circuit Boards

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Components with flat termination on package bottom side - so called Bottom Termination Components according to IPC-7093 - are the fastest growing component family on electronic circuit boards. A terminal pitch of 400µm meanwhile is standard for new packages and due to market requirements electronic component packages continously become smaller and smaller.
Due to many package variations and sometimes extremely area differences between thermal pads and the sum of peripheral pads fundamental knowledge is required for appropriate land dimensioning. The circuit board designer must know about processing risks of different component packages to design error free and save to manufacture circuit boards.
As the thickness of the smallest components meanwhile is in the range of 100µm and solder joints thickness very often is below 50µm, circuit board topology - soldermask and silksreen becomes a critical part and can dramatically influence reliability of electronic assemblies
The presentation adresses the risks of bottom terminated µ-Components and gives guidelines for dimensioning of landpattern and save processing of this package types.

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